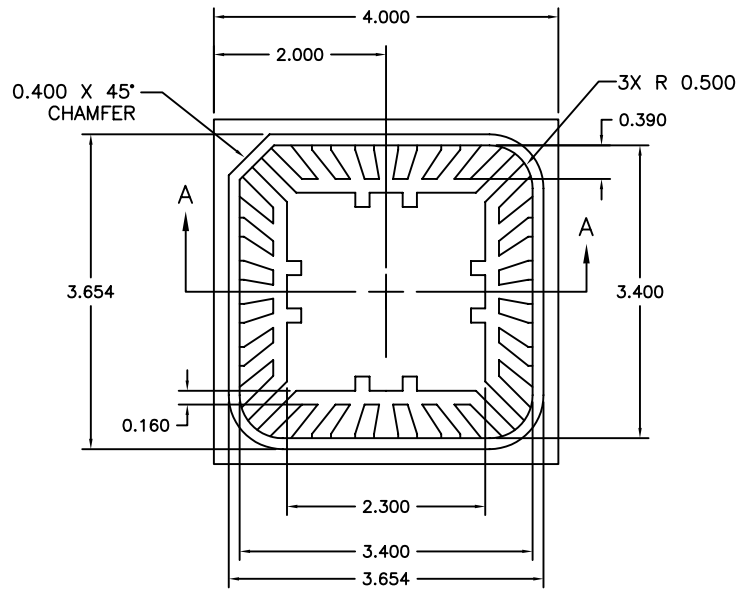
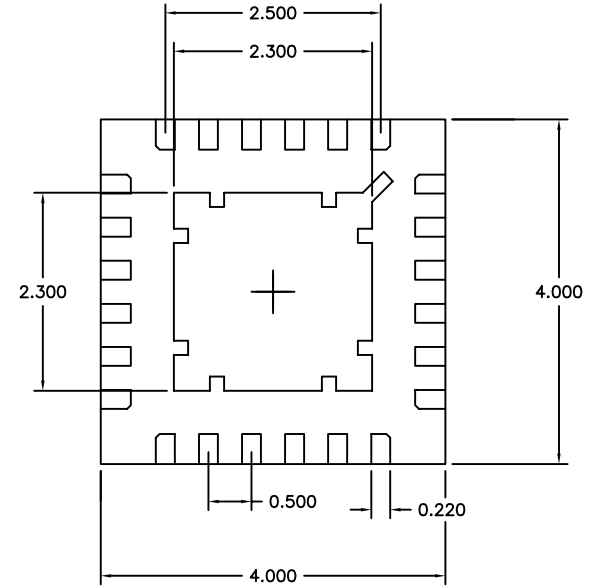
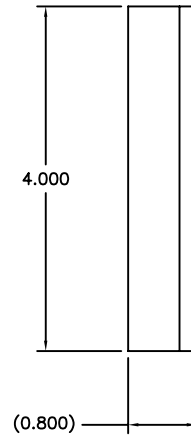


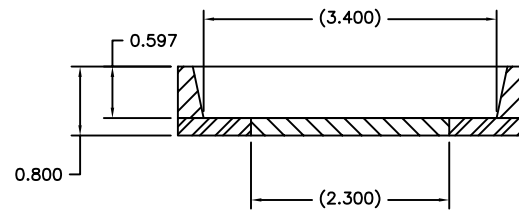
REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
10488	10/25/05	PRODUCTION RELEASE	D.BENANDO



TOP VIEW



BOTTOM VIEW



SECTION A-A

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 2. LEAD FRAME: COPPER, 194 FH.
 3. LEAD FINISH: FULL GOLD PLATE.
 4. FRAME THICKNESS: 0.2030 ± 0.0076.
 5. DIE PAD: 2.300mm X 2.300mm.
 6. JEDEC OUTLINE: MO-220 (VGGD-2)

	THIRD ANGLE PROJECTION
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE:	
X.XX ± 0.015	X.XXXX ± ---
X.XXX ± 0.050	ANGLES: ± 1°
DO NOT SCALE DRAWING	

DRAWN BY	W. GRIFFITTS	DATE	10/25/05
APP BY	P. FLASKERUD	DATE	10/25/05
CUSTOMER	---		
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SEMPAC, INC. Open-Pak™ Technologies www.sempac.com 568 E. WEDDELL DRIVE, SUITE 5 SUNNYVALE, CALIFORNIA 94089 PHONE: (408) 400-9002 FAX: (408) 400-9006			
24 Lead 4mm x 4mm MLP Open_pak			
SIZE	PART NO.	REV	
A	MLP4X4-24-OP-01	2	
SCALE	NONE	CAD FILE	MLP4X4-24-OP-01-R2.DWG
			SHEET 1 OF 1